

S/N 10/722,838

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon

Examiner: James M. Mitchell

Serial No.: 10/722,838

Group Art Unit: 2813

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Docket No.: 303.601US3

Title: METHOD OF PACKAGING AT A WAFER LEVEL

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on April 6, 2007. Please amend the above-identified patent application as follows.